

| Ref # | Hits | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|---|---|------------------|---------|------------------|
| S6    | 1039 | 257/698.ccls.   | US-PGPUB;<br>USPAT  | OR               | ON      | 2005/02/07 11:11 |
| S7    | 164  | S6 and (heat adj sink)  | US-PGPUB;<br>USPAT  | OR               | ON      | 2005/02/07 10:58 |
| S8    | 1083 | 257/700.ccls.   | US-PGPUB;<br>USPAT  | OR               | ON      | 2005/02/07 11:11 |
| S9    | 172  | S8 and (heat adj sink)  | US-PGPUB;<br>USPAT  | OR               | ON      | 2005/02/07 11:11 |
| S12   | 13   | ((("5014419") or ("5380681") or ("5432999") or ("5770476") or ("5869891") or ("5880024") or ("5908304") or ("5963795") or ("5973392") or ("6002177") or ("6020629") or ("6137163") or ("6188127"))).PN. | US-PGPUB;<br>USPAT  | OR               | OFF     | 2005/02/07 11:23 |
| S13   | 1    | ("6780672").PN.   | US-PGPUB;<br>USPAT  | OR               | OFF     | 2005/02/07 11:26 |
| S14   | 1    | ("20030022417").PN.   | US-PGPUB;<br>USPAT  | OR               | OFF     | 2005/02/07 12:27 |
| S15   | 70   | (heat adj sink) with copper with tungsten with alloy  | US-PGPUB;<br>USPAT  | OR               | ON      | 2005/02/07 12:28 |
| S17   | 154  | package and heat\$1sink and (substrate with opening)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/04/26 14:49 |
| S18   | 25   | S17 and (heat\$1sink with substrate with opening)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/04/26 15:35 |
| S19   | 2286 | (257/706.ccls. 257/712.ccls. 257/720.ccls.) not (257/E23.141.ccls. 257/E23.174.ccls. 257/E23.169.ccls. 257/698.ccls. 257/700.ccls.)   | US-PGPUB;<br>USPAT  | OR               | ON      | 2005/04/27 11:27 |
| S20   | 4490 | packag\$5 and optoelectronic  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/04/27 11:28 |

|     |        |   |   |    |    |                  |
|-----|--------|---|---|----|----|------------------|
| S21 | 326    | S20 and electroplat\$5  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/04/27 11:28 |
| S22 | 159    | S21 and (nickel Ni) and (gold Au)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/04/27 11:33 |
| S23 | 47     | S22 and pins  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/04/27 11:33 |
| S24 | 20     | "5014904"   | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 17:49 |
| S25 | 0      | heat\$1sink with (copper adj tungsen adj alloy)                                       | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 17:49 |
| S26 | 326830 | heat\$1sink with copper with tungsen wiht alloy                                       | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 17:50 |
| S27 | 0      | heat\$1sink with copper with tungsen with alloy                                       | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 17:50 |
| S28 | 0      | heat\$1sink with copper with tungsen  | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 17:50 |
| S29 | 18     | heat\$1sink with copper with tungsten with alloy                                      | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 18:49 |
| S30 | 512    | (ceramic with substrate) with plat\$5 with gold                                       | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 18:49 |
| S32 | 152    | S30 with nickel   | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 19:38 |
| S33 | 1      | heat\$1sink with braz\$5 with copper with silver with alloy                           | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 19:58 |
| S34 | 0      | braz\$5 with copper with silver with alloy with (strong\$3 better best) with adhesive | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 19:59 |
| S35 | 14     | braz\$5 with copper with silver with alloy with (strong\$3 better best)               | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 19:59 |
| S36 | 132    | plating with (silver and gold) with electrolytic\$5                                   | US-PGPUB;<br>USPAT  | OR | ON | 2005/05/27 21:02 |